

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

Claims 1-14. (Cancelled)

15. (Currently Amended) A method for forming a mold gate of a tape substrate, comprising:
forming an aperture of the mold gate in a flexible dielectric film of the tape substrate; and
concurrently patterning conductive lines and a support structure of the mold gate from the same
conductive film, the support at least partially overlapping the aperture.

16. (Currently Amended) The method of claim 15, further comprising:
securing ~~said~~ the conductive film to ~~said~~ the flexible dielectric film.

17. (Currently Amended) The method of claim 16, wherein ~~said~~ securing the
conductive film is effected before ~~said~~ forming an aperture of the mold gate.

18. (Currently Amended) The method of claim 17, wherein ~~said~~ forming an aperture
comprises etching the flexible dielectric film.

19. (Currently Amended) The method of claim 18, wherein ~~said~~ etching the flexible
dielectric film comprises at least one of wet etching and dry etching the flexible dielectric film.

20. (Currently Amended) The method of claim 16, wherein ~~said~~ securing the
conductive film is effected following ~~said~~ forming an aperture of the mold gate.

21. (Currently Amended) The method of claim 20, wherein ~~said~~ forming an aperture comprises mechanically removing material of the flexible dielectric film.

22. (Currently Amended) The method of claim 21, wherein ~~said~~ mechanically removing material comprises die cutting the flexible dielectric film.

23. (Currently Amended) The method of claim 15, wherein ~~said~~ concurrently patterning comprises:
forming a mask over ~~said~~ the conductive film; and
removing material of ~~said~~ the conductive film through apertures of ~~said~~ the mask.

24. (Currently Amended) The method of claim 23, wherein ~~said~~ removing material comprises etching ~~said~~ the conductive film.

25. (Currently Amended) The method of claim 15, further comprising:
coating sidewalls of ~~said~~ the aperture with a material that reduces or prevents adhesion of a packaging material to the mold gate.

26. (Currently Amended) A method for fabricating a tape substrate, comprising:
providing a flexible dielectric film;
forming an aperture of a mold gate in ~~said~~ the flexible dielectric film; and
substantially concurrently forming a support element of ~~said~~ the mold gate and conductive traces from a single conductive film laminated onto a surface of ~~said~~ the flexible dielectric film, the support structure at least partially overlapping the aperture.

27. (Currently Amended) The method of claim 26, wherein ~~said~~ providing ~~said~~ the flexible dielectric film comprises providing ~~said~~ the flexible dielectric film with ~~said~~ the single conductive film prelaminated onto ~~said~~ the surface thereof.

28. (Currently Amended) The method of claim 26, wherein ~~said~~ providing ~~said the~~ flexible dielectric film comprises providing ~~said the~~ flexible dielectric film without ~~said the~~ single conductive film on ~~said the~~ surface thereof.

29. (Currently Amended) The method of claim 28, further comprising:
laminating ~~said the~~ single conductive film onto ~~said the~~ surface of ~~said the~~ flexible dielectric film.

30. (Currently Amended) The method of claim 29, wherein ~~said~~ laminating is effected following ~~said~~ forming ~~said the~~ aperture.

31. (Currently Amended) The method of claim 30, wherein ~~said~~ forming ~~said the~~ aperture comprises mechanically forming ~~said the~~ aperture.

32. (Currently Amended) The method of claim 31, wherein ~~said~~ mechanically forming ~~said the~~ aperture comprises die cutting ~~said the~~ flexible dielectric film.

33. (Currently Amended) The method of claim 26, wherein ~~said~~ forming ~~said the~~ aperture comprises mechanically forming ~~said the~~ aperture.

34. (Currently Amended) The method of claim 33, wherein ~~said~~ mechanically forming ~~said the~~ aperture comprises die cutting ~~said the~~ flexible dielectric film.

35. (Currently Amended) The method of claim 26, wherein ~~said~~ forming ~~said the~~ aperture comprises:
forming a mask on a surface of ~~said the~~ flexible dielectric film; and
removing material of ~~said the~~ flexible dielectric film through apertures of ~~said the~~ mask.

36. (Currently Amended) The method of claim 35 wherein ~~said~~-removing comprises etching ~~said-the~~ material of ~~said-the~~ flexible dielectric film.

37. (Currently Amended) The method of claim 36, wherein ~~said~~-etching comprises at least one of dry etching and wet etching ~~said-the~~ material of ~~said-the~~ flexible dielectric film.

38. (Currently Amended) The method of claim 26, wherein ~~said~~-forming ~~said-the~~ aperture is effected at a location which is external to an outer boundary of an area of ~~said-the~~ flexible dielectric film where a finished tape substrate is to be located.

39. (Currently Amended) The method of claim 26, wherein ~~said~~-substantially concurrently forming comprises:
forming a mask over ~~said-the~~ single conductive film; and
removing material of ~~said-the~~ single conductive film through apertures of ~~said-the~~ mask.

40. (Currently Amended) The method of claim 39, wherein ~~said~~-removing material comprises etching ~~said-the~~ single conductive film.

41. (Currently Amended) The method of claim 26, further comprising:
coating sidewalls of ~~said-the~~ aperture with a material that reduces or prevents adhesion of a packaging material to ~~said-the~~ mold gate.

42. (Currently Amended) The method of claim 26, further comprising plating conductive structures of ~~said-the~~ support element.

Claims 43-50. (Cancelled)